

Product Change Notification - KSRA-05EGLK602

Date: 15 Jan 2018
Product Category: General Purpose LED Drivers
Notification subject: CCB 3047 Final Notice: Qualification of MMT as an additional assembly site for selected Supertex products available in 8L SOIC package.

Notification text:
PCN Status:
 Final notification.

PCN Type:
 Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected Supertex products available in 8L SOIC package.

Pre Change:

Assembled at NSEB assembly site using, 8200T die attach and EME-G600 molding compound material.

Post Change:

Assembled at NSEB assembly site using, 8200T die attach and EME-G600 molding compound material and MMT assembly site using, 84-1LMISR4 die attach and G600V molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	UTAC Thai Limited (NSEB)	UTAC Thai Limited (NSEB)	Microchip Technology Thailand -Branch (MMT)
Wire material	Au	Au	Au
Die attach material	8200T	8200T	84-1LMISR4
Molding compound material	EME-G600	EME-G600	G600V
Lead frame material	C194	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MMT as an additional assembly site

Change Implementation Status:
In Progress

Estimated First Ship Date:
February 15, 2018 (date code: 1807)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	September 2017					January 2018					February 2018			
	35	36	37	38	39	01	02	03	04	05	06	07	08	09
Initial PCN Issue Date				X										
Qual Report Availability								X						
Final PCN Issue Date								X						
Estimated Implementation Date												X		

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
September 21, 2017: Issued initial notification.
January 15, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on February 15, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):
[PCN_KSRA-05EGLK602_Qual Report.pdf](#)
[PCN_KSRA-05EGLK602_Affected CPN.pdf](#)
[PCN_KSRA-05EGLK602_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-05EGLK602
CATALOG_PART_NBR
HV9801ALG-G
HV9803BLG-G
HV9803BLG-G-S376
HV9803LG-G
HV9803LG-G-S374
HV9861ALG-G
HV9910CLG-G
HV9910CSG-G